Non-Inverting 3-State Buffer

NL17SZ125

The NL17SZ125 is a single non−inverting 3−state buffer in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.3 ns t_{PD} at V_{CC} = 5 V (typ)
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in SC−88A, SC−74A, TSOP−5, SOT−553, SOT−953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant
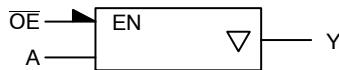
Figure 1. Logic Symbol

MARKING DIAGRAMS

	SC−88A **DF SUFFIX** **CASE 419A**	XX M▪ ○
	SC−74A **DBV SUFFIX** **CASE 318BQ**	XXX M▪ ○
	TSOP−5 **DT SUFFIX** **CASE 483**	XX M▪
	SOT−553 **XV5 SUFFIX** **CASE 463B**	XX M▪ ○ ▪
	SOT−953 **P5 SUFFIX** **CASE 527AE**	X M
	UDFN6 **1.45 x 1.0** **CASE 517AQ**	XM
	UDFN6 **1.0 x 1.0** **CASE 517BX**	X M
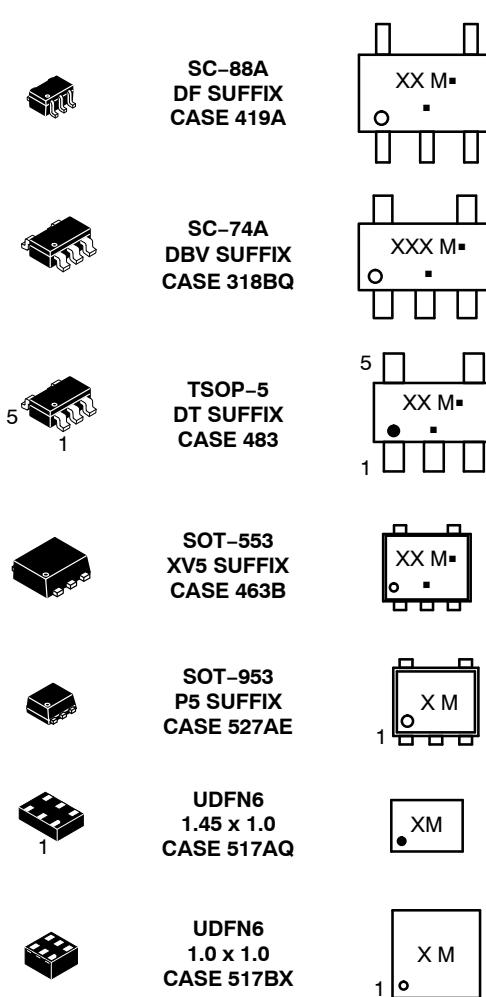
XX	= Specific Device Code
M	= Date Code*
▪	= Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

NL17SZ125
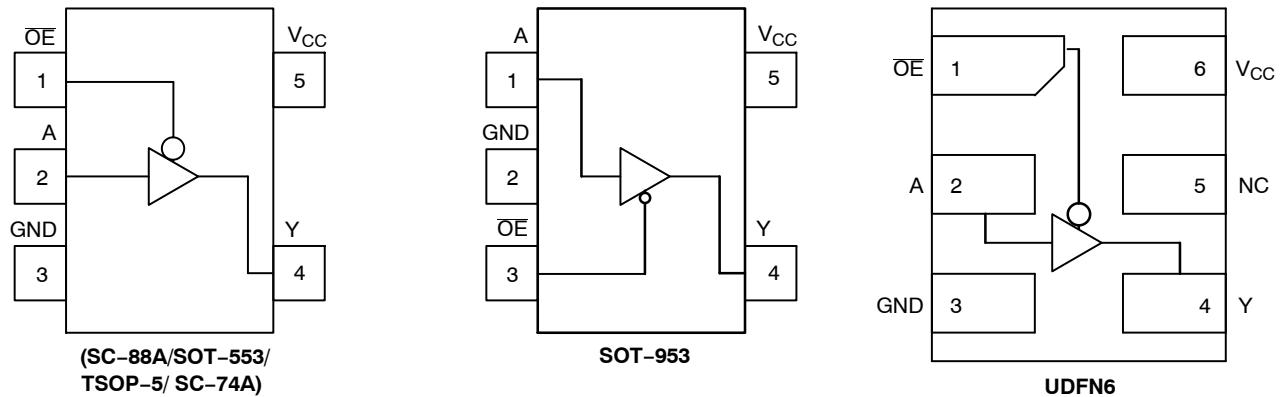
Figure 2. Pinout (Top View)

PIN ASSIGNMENT
(SC−88A/SOT−553/ TSOP−5/SC−74A)

Pin	Function
1	$\overline{OE}$
2	A
3	GND
4	Y
5	V_{CC}

PIN ASSIGNMENT (SOT−953)

Pin	Function
1	A
2	GND
3	$\overline{OE}$
4	Y
5	V_{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	$\overline{OE}$
2	A
3	GND
4	Y
5	NC
6	V_{CC}

FUNCTION TABLE

Input		Output
$\overline{OE}$	A	Y
L	L	L
L	H	H
H	X	Z

X = Don't Care

NL17SZ125

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V_{CC}	DC Supply Voltage	(NLV)	−0.5 to +7.0 −0.5 to +6.5	V
V_{IN}	DC Input Voltage	(NLV)	−0.5 to +7.0 −0.5 to +6.5	V
V_{OUT}	DC Output Voltage (NLV)	Active−Mode (High or Low State) Tri−State Mode (Note 1) Power−Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC} + 0.5 −0.5 to +7.0 −0.5 to +7.0	V
	DC Output Voltage	(NL17SZ125P5T5G−L22088 Only)	−0.5 to V_{CC} + 0.5	
	DC Output Voltage	Active−Mode (High or Low State) Tri−State Mode (Note 1) Power−Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC} + 0.5 −0.5 to +6.5 −0.5 to +6.5	
I_{IK}	DC Input Diode Current	V_{IN} < GND	−50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < GND	−50	mA
	DC Output Diode Current	(NL17SZ125P5T5G−L22088 Only)	±50	
I_{OUT}	DC Output Source/Sink Current		±50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC−88A SC−74A SOT−553 SOT−953 UDFN6	377 320 324 254 154	°C/W
P_D	Power Dissipation in Still Air	SC−88A SC−74A SOT−553 SOT−953 UDFN6	332 390 386 491 812	mW
MSL	Moisture Sensitivity		Level 1	−
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	−
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)		± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Applicable to devices with outputs that may be tri−stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm−by−1inch, 2 ounce copper trace no air flow per JESD51−7.
3. HBM tested to ANSI/ESDA/JEDEC JS−001−2017. CDM tested to EIA/JESD22−C101−F. JEDEC recommends that ESD qualification to EIA/JESD22−A115−A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

NL17SZ125

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		1.65	5.5	V
V_{IN}	DC Input Voltage		0	5.5	V
V_{OUT}	DC Output Voltage	Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V_{CC} = 0 V)	0 0 0	V_{CC} 5.5 5.5	V
	DC Output Voltage	(NL17SZ125P5T5G–L22088 Only)	0	V_{CC}	
T_A	Operating Temperature Range		−55	+125	°C
t_r , t_f	Input Rise and Fall Time (NLV)	V_{CC} = 3.0 V to 3.6 V V_{CC} = 4.5 V to 5.5 V	0 0	100 20	ns/V
	Input Rise and Fall Time	V_{CC} = 1.65 V to 1.95 V V_{CC} = 2.3 V to 2.7 V V_{CC} = 3.0 V to 3.6 V V_{CC} = 4.5 V to 5.5 V	0 0 0 0	20 20 10 5	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	T_A = 25°C			−55°C ≤ T_A ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
V_{IH}	High–Level Input Voltage (NLV and NL17SZ125P5T5G–L22088)		1.65 to 1.95	0.75 x V_{CC}	–	–	0.75 x V_{CC}	–	V
			2.3 to 5.5	0.70 x V_{CC}	–	–	0.70 x V_{CC}	–	
	High–Level Input Voltage		1.65 to 1.95	0.65 x V_{CC}	–	–	0.65 x V_{CC}	–	V
			2.3 to 5.5	0.70 x V_{CC}	–	–	0.70 x V_{CC}	–	
V_{IL}	Low–Level Input Voltage (NLV and NL17SZ125P5T5G–L22088)		1.65 to 1.95	–	–	0.25 x V_{CC}	–	0.25 x V_{CC}	V
			2.3 to 5.5	–	–	0.30 x V_{CC}	–	0.30 x V_{CC}	
	Low–Level Input Voltage		1.65 to 1.95	–	–	0.35 x V_{CC}	–	0.35 x V_{CC}	V
			2.3 to 5.5	–	–	0.30 x V_{CC}	–	0.30 x V_{CC}	
V_{OH}	High–Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OH} = −100 μA I_{OH} = −4 mA I_{OH} = −8 mA I_{OH} = −12 mA I_{OH} = −16 mA I_{OH} = −24 mA I_{OH} = −32 mA	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V_{CC} – 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V_{CC} 1.4 2.1 2.4 2.7 2.5 4.0	– – – – – – –	V_{CC} – 0.1 1.29 1.9 2.2 2.4 2.3 3.8	– – – – – – –	V
V_{OL}	Low–Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OL} = 100 μA I_{OL} = 4 mA I_{OL} = 8 mA I_{OL} = 12 mA I_{OL} = 16 mA I_{OL} = 24 mA I_{OL} = 32 mA	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	– – – – – – –	0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55	– – – – – – –	0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I_{IN}	Input Leakage Current	V_{IN} = 5.5 V or GND	1.65 to 5.5	–	–	±0.1	–	±1.0	μA
I_{OZ}	3–State Output Leakage Current	V_{OUT} = 0 V to 5.5 V	1.65 to 5.5	–	–	±0.5	–	±5.0	μA

DC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Units
				Min	Typ	Max	Min	Max	
I_{OFF}	Power Off Leakage Current	$V_{IN} = 5.5$ V or $V_{OUT} = 5.5$ V	0	–	–	1.0	–	10	μA
	Power Off Leakage Current (NL17SZ125P5T5G–L22088 Only)	$V_{IN} = 5.5$ V	0	–	–	1.0	–	10	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	–	–	1.0	–	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Units
				Min	Typ	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	$R_L = 1$ MΩ, $C_L = 15$ pF	1.65 to 1.95	–	6.0	10	–	10.5	ns
		$R_L = 1$ MΩ, $C_L = 15$ pF	2.3 to 2.7	–	3.4	7.5	–	8.0	
		$R_L = 1$ MΩ, $C_L = 15$ pF	3.0 to 3.6	–	2.5	5.2	–	5.5	
		$R_L = 500$ Ω, $C_L = 50$ pF		–	2.9	5.7	–	6.0	
		$R_L = 1$ MΩ, $C_L = 15$ pF	4.5 to 5.5	–	2.0	4.5	–	4.8	
		$R_L = 500$ Ω, $C_L = 50$ pF		–	2.3	5.0	–	5.3	
t_{PZH}, t_{PZL}	Output Enable Time, $\overline{OE}$ to Y (Figures 3 and 4)		1.65 to 1.95	–	6.5	9.5	–	10	ns
			2.3 to 2.7	–	3.6	8.5	–	9.0	
			3.0 to 3.6	–	2.8	6.2	–	6.5	
			4.5 to 5.5	–	2.0	5.5	–	5.8	
t_{PHZ}, t_{PLZ}	Output Disable Time, $\overline{OE}$ to Y (Figures 3 and 4)		1.65 to 1.95	–	5.0	10	–	10.5	ns
			2.3 to 2.7	–	3.3	8.0	–	8.5	
			3.0 to 3.6	–	2.7	5.7	–	6.0	
			4.5 to 5.5		2.6	4.7	–	5.0	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	2.5	pF
C_{OUT}	Output Capacitance	$V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	2.5	pF
C_{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, $V_{CC} = 3.3$ V, $V_{IN} = 0$ V or V_{CC} 10 MHz, $V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	9 11	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz
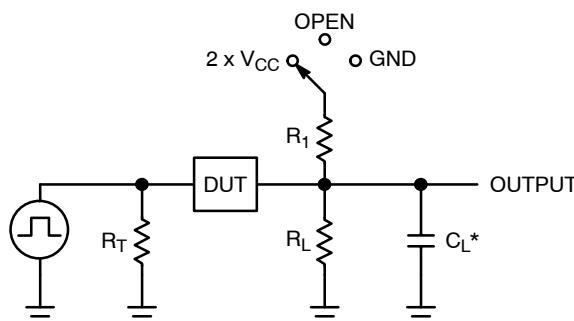
Figure 3. Test Circuit

Test	Switch Position	C_L, pF		R_L, Ω	R_1, Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table			
t_{PLZ} / t_{PZL}	2 x V_{CC}	50		500	500
t_{PHZ} / t_{PZH}	GND	50		500	500

X = Don't Care
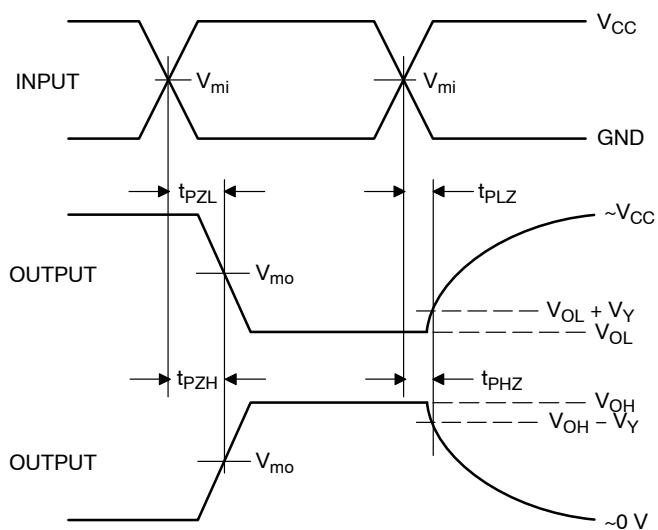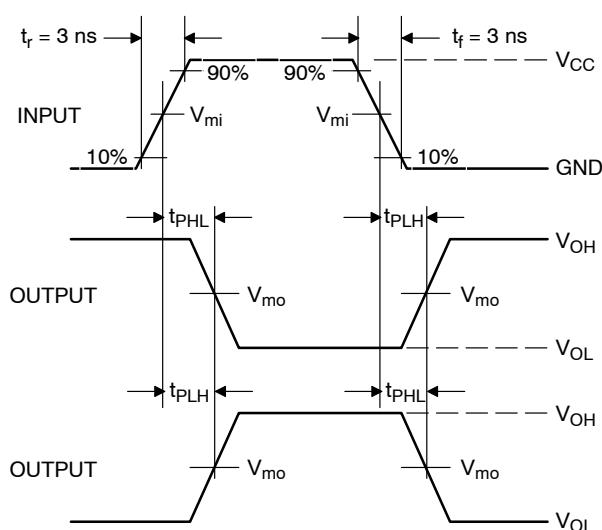
Figure 4. Switching Waveforms

V_{CC}, V	V_{mi}, V	V_{mo}, V		V_Y, V
		t_{PLH}, t_{PHL}	t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}	
1.65 to 1.95	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
2.3 to 2.7	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

NL17SZ125

DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping†
NL17SZ125DFT2G	SC−88A	M0	Q4	3000 / Tape & Reel
NL17SZ125DFT2G−F22038**	SC−88A	M0	Q4	3000 / Tape & Reel
NLV17SZ125DFT2G*	SC−88A	M0	Q4	3000 / Tape & Reel
NL17SZ125DBVT1G	SC−74A	M0	Q4	3000 / Tape & Reel
NL17SZ125DTT1G**	TSOP−5	M0	Q4	3000 / Tape & Reel
NL17SZ125XV5T2G	SOT−553	M0	Q4	4000 / Tape & Reel
NL17SZ125XV5T2G−L22087**	SOT−553	M0	Q4	4000 / Tape & Reel
NL17SZ125P5T5G	SOT−953	Q (Rotated 180° CW)	Q2	8000 / Tape & Reel
NL17SZ125P5T5G−L22088	SOT−953	Q (Rotated 180° CW)	Q2	8000 / Tape & Reel
NL17SZ125MU1TCG (In Development)	UDFN6, 1.45 x 1.0, 0.5P	TBD	Q4	3000 / Tape & Reel
NL17SZ125MU3TCG	UDFN6, 1.0 x 1.0, 0.35P	A	Q4	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.
** Please refer to NLV specifications for this device.

Pin 1 Orientation in Tape and Reel

NL17SZ125
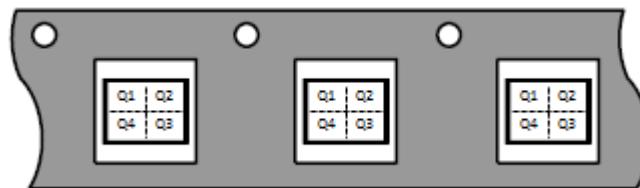
PACKAGE DIMENSIONS

SC−88A (SC−70−5/SOT−353)
CASE 419A−02
ISSUE L
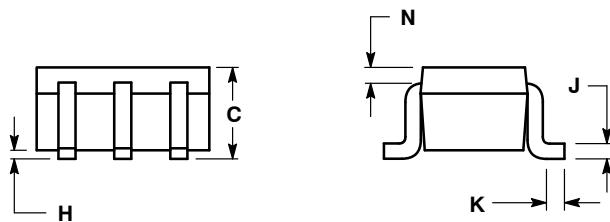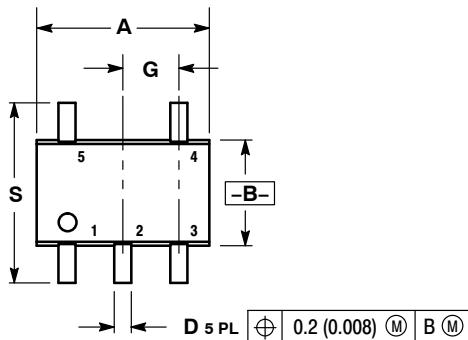
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A−01 OBSOLETE. NEW STANDARD 419A−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

D 5 PL ⊕ | 0.2 (0.008) Ⓜ | B Ⓜ

SOLDER FOOTPRINT

0.50 / 0.0197

0.65 / 0.025

0.65 / 0.025

0.40 / 0.0157

1.9 / 0.0748

SCALE 20:1 $\left(\dfrac{mm}{inches}\right)$
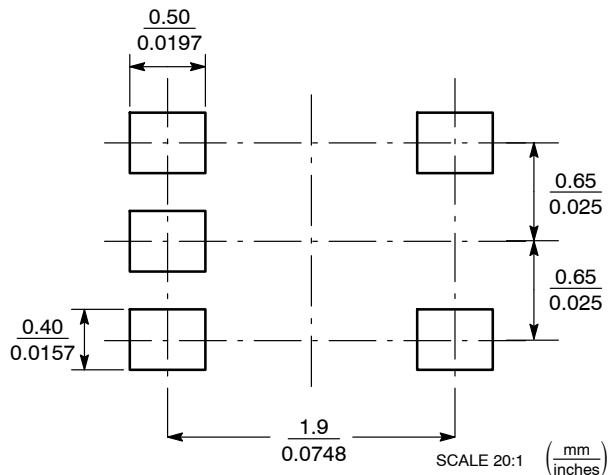
STYLE 1:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 3:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6:
PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

NL17SZ125

PACKAGE DIMENSIONS

SC−74A
CASE 318BQ
ISSUE B
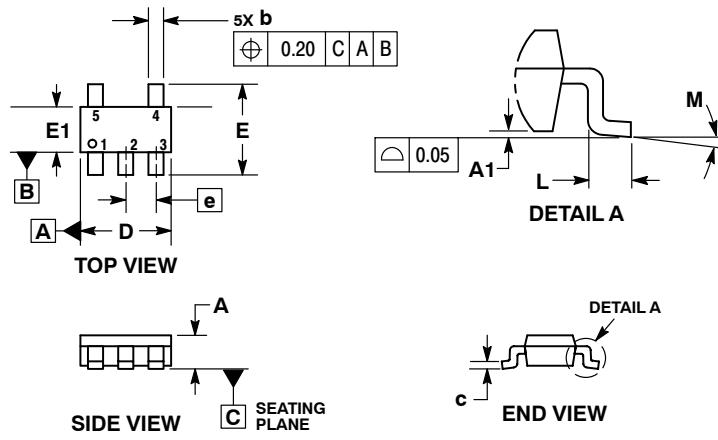
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0 °	10 °
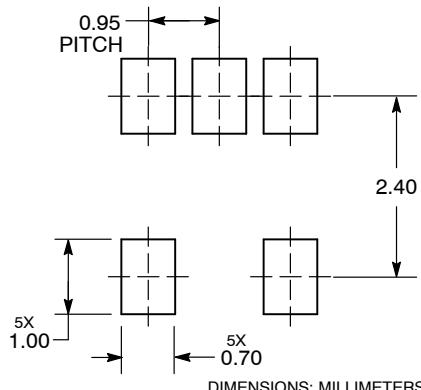
TOP VIEW

SIDE VIEW

SEATING PLANE

DETAIL A

END VIEW

RECOMMENDED SOLDERING FOOTPRINT*

0.95 PITCH

2.40

5X 1.00

5X 0.70

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ125

PACKAGE DIMENSIONS

TSOP−5
CASE 483
ISSUE N
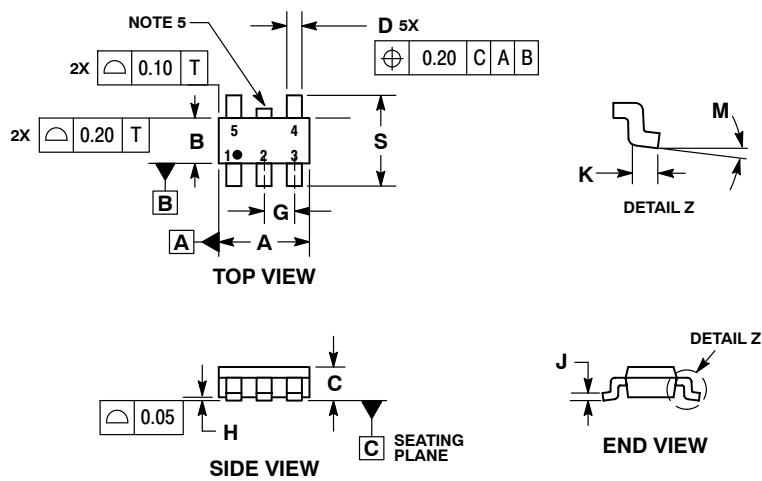
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

DIM	MILLIMETERS	
	MIN	MAX
A	2.85	3.15
B	1.35	1.65
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0 °	10 °
S	2.50	3.00

SOLDERING FOOTPRINT*
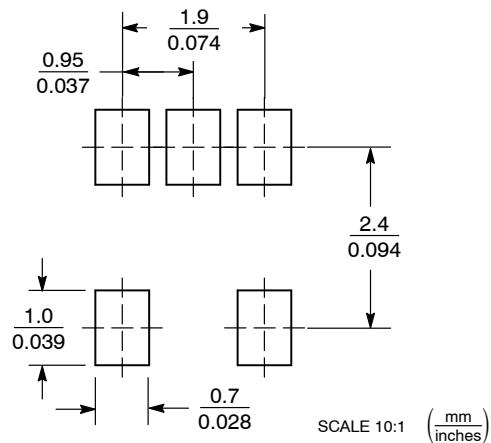
SCALE 10:1 $\left(\dfrac{mm}{inches}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ125

PACKAGE DIMENSIONS

SOT−553, 5 LEAD
CASE 463B
ISSUE C
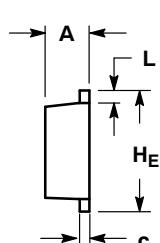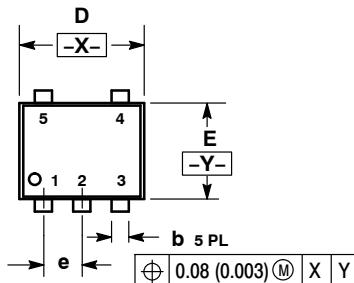
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.55	1.60	1.65	0.061	0.063	0.065
E	1.15	1.20	1.25	0.045	0.047	0.049
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.55	1.60	1.65	0.061	0.063	0.065
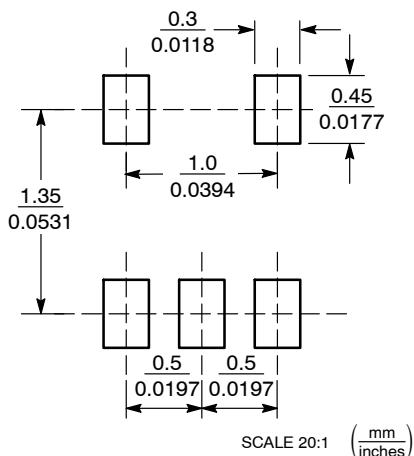
$\oplus$ | 0.08 (0.003) (M) | X | Y

SOLDERING FOOTPRINT*

SCALE 20:1 $\left(\dfrac{mm}{inches}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ125

PACKAGE DIMENSIONS

SOT−953
CASE 527AE
ISSUE E
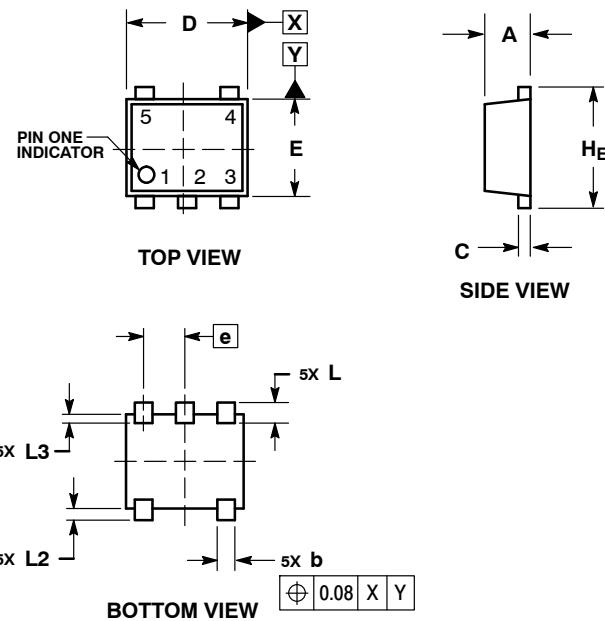
TOP VIEW

SIDE VIEW

BOTTOM VIEW

⊕ | 0.08 | X | Y

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35 BSC		
H_E	0.95	1.00	1.05
L	0.175 REF		
L2	0.05	0.10	0.15
L3	–––	–––	0.15

SOLDERING FOOTPRINT*
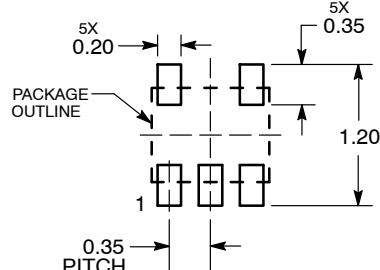
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ125

PACKAGE DIMENSIONS

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O
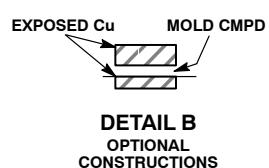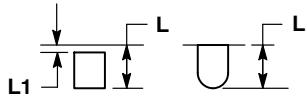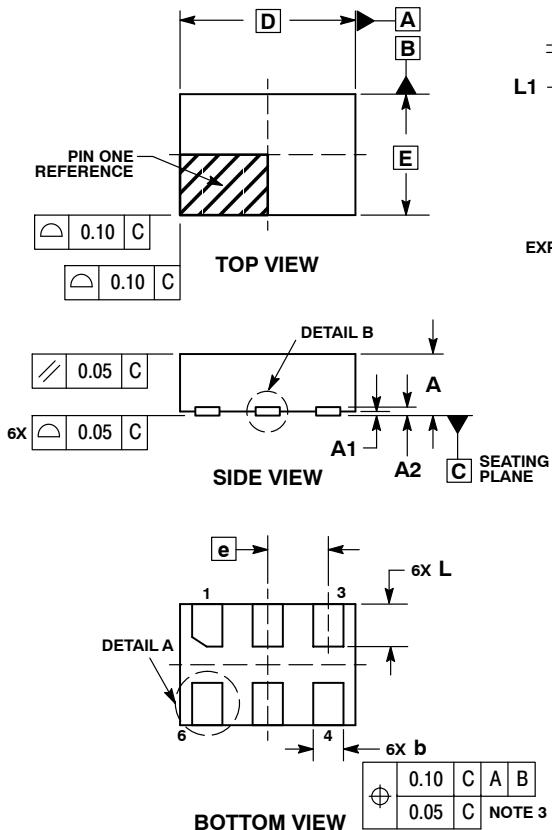
TOP VIEW

PIN ONE
REFERENCE

SIDE VIEW

6X

BOTTOM VIEW

DETAIL A
OPTIONAL
CONSTRUCTIONS

DETAIL B
OPTIONAL
CONSTRUCTIONS

EXPOSED Cu   MOLD CMPD

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	–––	0.15

MOUNTING FOOTPRINT
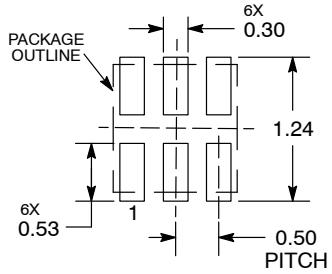
PACKAGE
OUTLINE

6X
0.30

1.24

6X
0.53

1

0.50
PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ125

PACKAGE DIMENSIONS

UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O
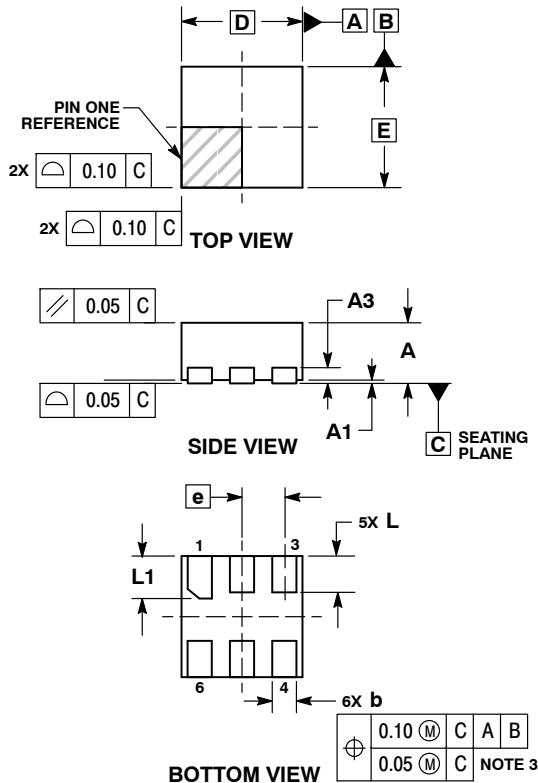
TOP VIEW

SIDE VIEW

BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

◊